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MT29UZ4B8DZZHGPB-107 W

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Data Sheets (1)

Data Sheet

<u>A</u>

221-Ball MCP: 4Gb NAND Flash and 8Gb Mobile LPDDR3 (J84Z) Data Sheet

4Gb x8 NAND (M60A) and 8Gb Single-Channel LPDDR3 (V01M) MCP; MT29UZ4B8DZZHGPB-107 W.84Z

File Type: PDF **Updated: 12/2016**

Embedded **Multichip Packages** NAND LPDDR3 NAND-Based MCP

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Specs

Orderable Parts for: MT29UZ4B8DZZHGPB-107 W

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	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29UZ4B8DZZHGPB-107 WES.84Z	Obsolete	N/A	JYA16	N/A	N/A	No		N/A

Detailed Specifications

Part Status Code	Obsolete	NAND Density	4Gb	DRAM Type	LPDDR3	DRAM Density	8Gb
Bus Width	x16	Secondary Bus Width	x16	RoHS	Yes	Voltage	1.8V
Package	WFBGA	Pin Count	221-ball	Clock Rate	933 MHz	Operating Temp	-30C to +85C

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

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China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

See All NAND-Based MCP Documentation

Technical Notes

SEARCH (2) NAND-BASED MCP TECHNICAL NOTES

Technical Notes

TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

File Type: PDF

Updated: 02/14/2013

DDR SDRAM DDR2 SDRAM DDR3 SDRAM DDR3L-RS See More Tags

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Technical Notes

TN-10-08: Thermal Implications for LPDDR Die Stacks (PDF)

Multichip Packages NAND-Based MCP

Mobile

(TN-10-08) This technical note presents a case study of a handset simulation in which an LPDRAM is stacked on an application processor (PoP) and the resulting thermal-profile modeling. This note also explains how thermal detection features included in LPDDR and LPDDR2 can be used to...

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Updated: 07/26/2010

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Micron Component and Module Packaging (PDF)

(CSN-16) Explanation of Micron packaging labels and procedures.

File Type: PDF

Updated: 06/29/2017

Client Storage Cloud Cloud Data Center See More Tags

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PoP User Guide (PDF)

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(CSN-34) Provides several well-established guidelines for package-on-package (PoP) semiconductor package design and assembly, which requires unique considerations in both the up-front design and the manufacturing process.

File Type: PDF

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SEARCH (2) NAND-BASED MCP CUSTOMER SERVICE NOTE

Where to Buy

Orderable Parts

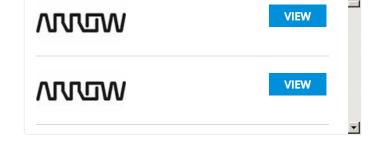
	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29UZ4B8DZZHGPB-107 WES.84Z	Obsolete	N/A	JYA16	N/A	N/A	No		N/A

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